

Chip Scale Review

2019 Editorial Calendar

(Editorial close date: 12/1/2018)

January • February

Industry Events * indicates show distribution

New test methodologies for 5G

RF/OTA

Thermal debonding and warpage in FOWLP

W2W/D2W & other bonding advances for 3D ICs

Temporary bonding & the challenges of cleaning post debond

Discontinuities drive data integration

IC packaging for Moore's Law

Heterogeneous integration

Thin wafer handling

- **APEX Expo**
San Diego, CA (Jan 26-31)
- **3D & Systems Summit**
Dresden, Germany (Jan 28-30)
- **SMTA Pan Pac Microelectronics Symposium**
Kauai, Hawaii (Feb 11-14)
- **FLEX / MEMS & Sensors Technical Congress**
Monterey, CA (Feb 18-21)

Ad Space Close Jan 18 - Ad Materials Close Jan 25

(Editorial close date: 2/28/19)

March • April

Industry Events * indicates show distribution

High density advanced packaging

3D IC metrology

3D system packaging

Electroplating models for 3D TSVs

Failure relief in WLP & PLP polymer layers

Customization of Electroplating Chemistries

Probe technology Q&A

Packaging of Implantable Devices

Power devices

- **TestConX**
Mesa, AZ (March 3-6)
- **IMAPS Device Packaging**
Fountain Hills, AZ (March 4-7)
- **SEMI-THERM**
San Jose, CA (March 18-22)
- **SEMICON China**
Shanghai, China (March 20-22)
- **ISS Europe**
Milan, Italy (March 31-April 2)

Ad Space Close Mar 13 - Materials Close Mar 22

(Editorial close date: 4/1)

May • June

Industry Events * indicates show distribution

Glass carriers for temporary bonding

High-density and high-bandwidth C2C connections

Multi-die/ substrate heterogeneous packages

Wafer scribing/dicing

Automotive

Inspection for advanced packaging processes

RF, Final test

Smart devices and applications

Bonding/debonding

- **SEMICON SE Asia**
Kuala Lumpur, Malaysia (May 7-9)
- **ECTC**
Las Vegas, NV (May 28-31)
- **IEEE/SW Test Workshop (SWTW)**
San Diego, CA (June 2-5)
- **Sensors Expo**
San Jose, CA (June 25-27)
- **SEMICON West**
San Francisco, CA (July 9-11)

Ad Space Close May 8 - Ad Materials Close May 17

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